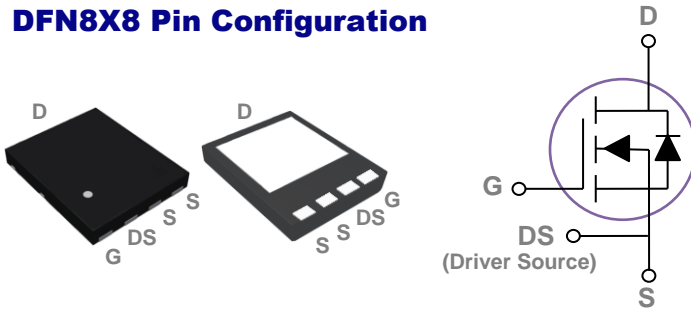


General Description

These N-Channel enhancement mode power field effect transistors are using super junction MOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN8X8 Pin Configuration



| | | |
|-------|-------|-----|
| BVDSS | RDSON | ID |
| 650V | 320mΩ | 14A |

Features

- 650V, 14A, $R_{DS(ON)} = 320m\Omega @ V_{GS} = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

Applications

- PFC Power Supply Stages
- Motor Control
- DC-DC Converters
- Adapter

Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

| Symbol | Parameter | Rating | Units |
|-----------|--|------------|---------------|
| V_{DS} | Drain-Source Voltage | 650 | V |
| V_{GS} | Gate-Source Voltage | ± 30 | V |
| I_D | Drain Current – Continuous ($T_c=25^\circ C$) | 14 | A |
| | Drain Current – Continuous ($T_c=100^\circ C$) | 8.8 | A |
| I_{DM} | Drain Current – Pulsed ¹ | 56 | A |
| EAS | Single Pulse Avalanche Energy ² | 290 | mJ |
| P_D | Power Dissipation ($T_c=25^\circ C$) | 114 | W |
| | Power Dissipation – Derate above $25^\circ C$ | 0.91 | W/ $^\circ C$ |
| T_{STG} | Storage Temperature Range | -55 to 150 | $^\circ C$ |
| T_J | Operating Junction Temperature Range | -55 to 150 | $^\circ C$ |

Thermal Characteristics

| Symbol | Parameter | Typ. | Max. | Unit |
|-----------------|--|------|------|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to ambient | --- | 62 | $^\circ C/W$ |
| $R_{\theta JC}$ | Thermal Resistance Junction to Case | --- | 1.1 | $^\circ C/W$ |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)
Off Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|---|------|------|------|------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =1mA | 650 | --- | --- | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =650V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =520V, V _{GS} =0V, T _J =100°C | --- | --- | 10 | uA |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±30V, V _{DS} =0V | --- | --- | ±100 | nA |

On Characteristics

| | | | | | | |
|---------------------|-----------------------------------|--|-----|-----|-----|----|
| R _{DS(ON)} | Static Drain-Source On-Resistance | V _{GS} =10V, I _D =6A | --- | 270 | 320 | mΩ |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 2 | 3 | 4 | V |

Dynamic and switching Characteristics

| | | | | | | |
|---------------------|-------------------------------------|---|-----|-----|------|----|
| Q _g | Total Gate Charge ^{3, 4} | V _{DS} =350V, V _{GS} =10V, I _D =14A | --- | 26 | 40 | nC |
| Q _{gs} | Gate-Source Charge ^{3, 4} | | --- | 5 | 8 | |
| Q _{gd} | Gate-Drain Charge ^{3, 4} | | --- | 18 | 26 | |
| T _{d(on)} | Turn-On Delay Time ^{3, 4} | V _{DS} =350V, V _{GS} =10V, R _G =25Ω I _D =14A | --- | 20 | 30 | ns |
| T _r | Rise Time ^{3, 4} | | --- | 43 | 65 | |
| T _{d(off)} | Turn-Off Delay Time ^{3, 4} | | --- | 91 | 137 | |
| T _f | Fall Time ^{3, 4} | | --- | 42 | 63 | |
| C _{iss} | Input Capacitance | V _{DS} =350V, V _{GS} =0V, F=1MHz | --- | 910 | 1360 | pF |
| C _{oss} | Output Capacitance | | --- | 28 | 45 | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 2.4 | 5 | |
| R _g | Gate resistance | V _{GS} =0V, V _{DS} =0V, F=1MHz | --- | 7 | --- | Ω |

Drain-Source Diode Characteristics and Maximum Ratings

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|---------------------------|---|------|------|------|------|
| I _S | Continuous Source Current | V _G =V _D =0V, Force Current | --- | --- | 14 | A |
| I _{SM} | Pulsed Source Current | | --- | --- | 28 | A |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1.2 | V |
| t _{rr} | Reverse Recovery Time | V _R =400V, I _S =10A | --- | 330 | --- | ns |
| Q _{rr} | Reverse Recovery Charge | di/dt=100A/μs, T _J =25°C | --- | 4.1 | --- | uC |

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

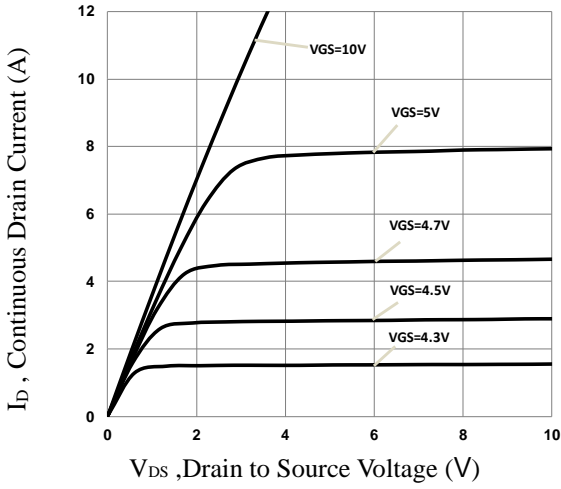


Fig.1 Typical Output Characteristics

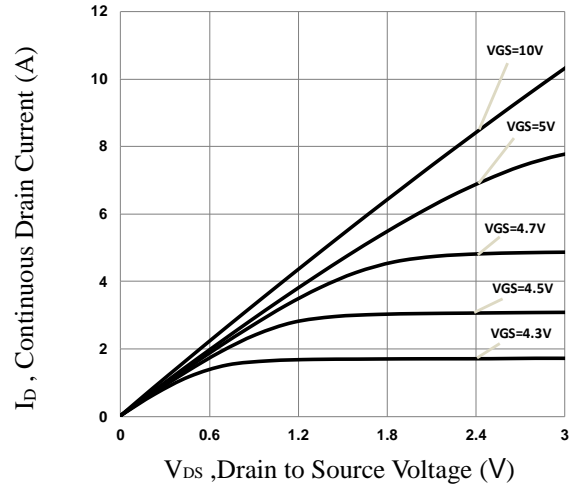


Fig.2 Typical Output Characteristics

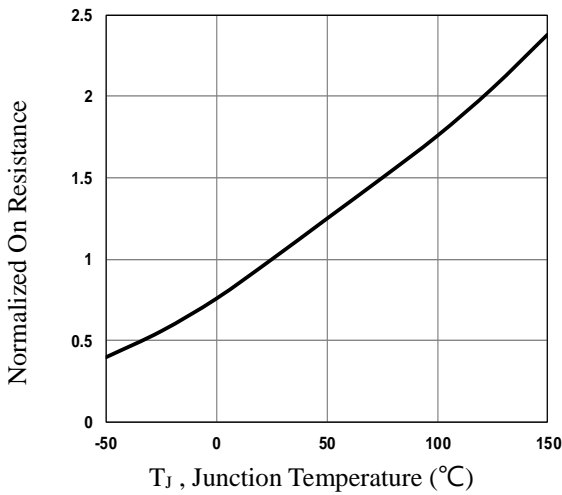


Fig.3 Normalized $R_{DS(on)}$ vs. T_J

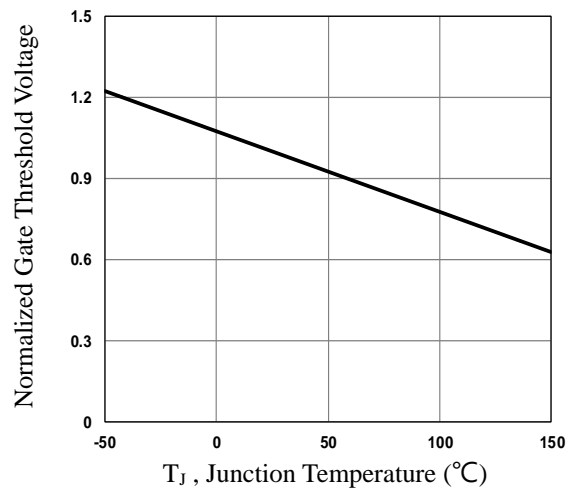


Fig.4 Normalized V_{th} vs. T_J

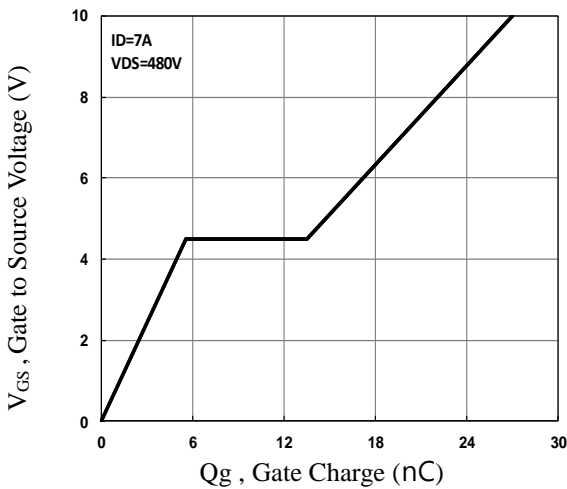


Fig.5 Gate Charge Characteristics

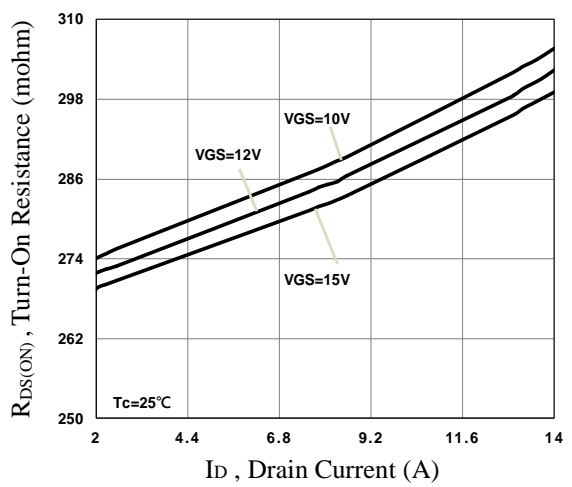


Fig.6 Turn-On Resistance vs. I_D

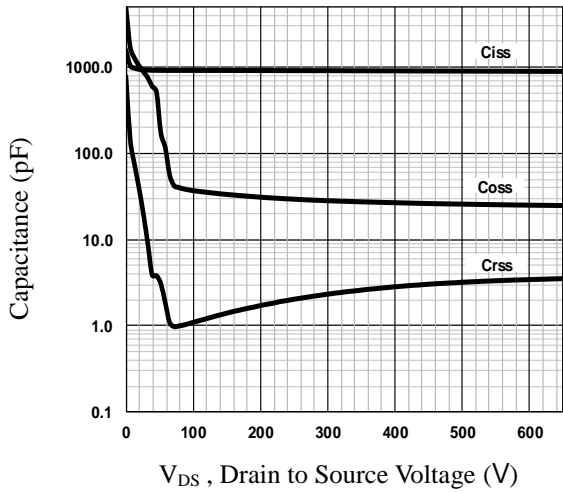


Fig.7 Capacitance Characteristics

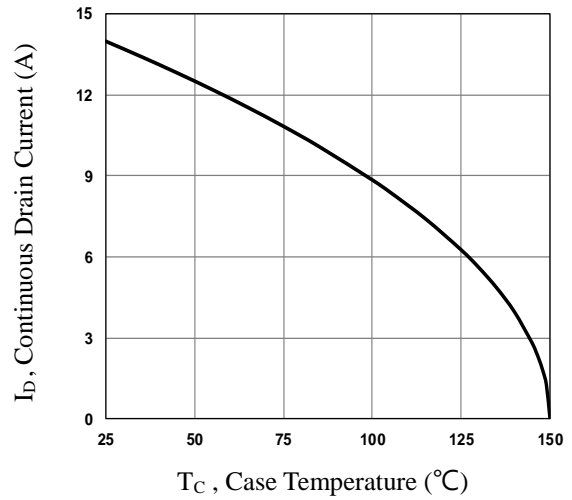


Fig.8 Continuous Drain Current vs. T_c

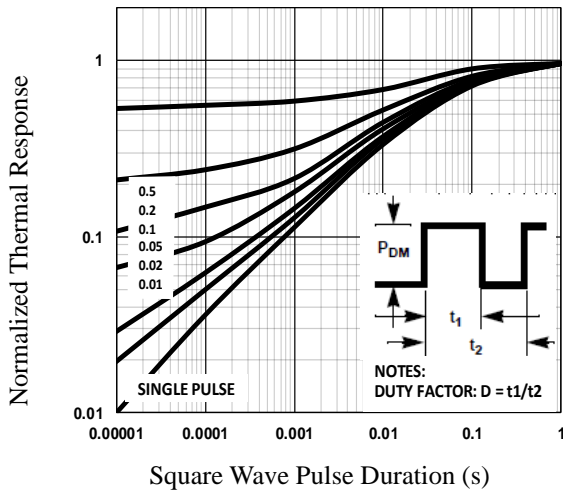


Fig.9 Normalized Transient Impedance

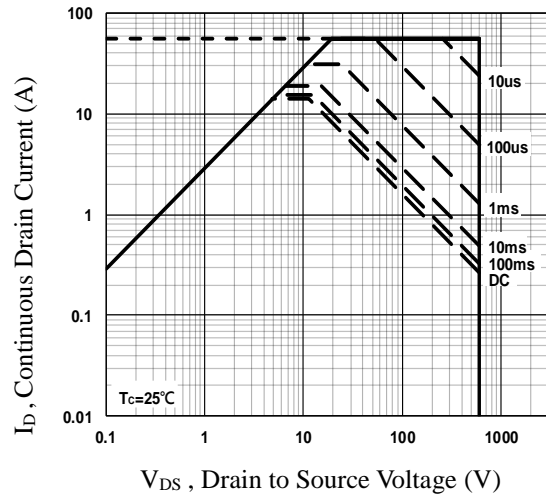


Fig.10 Maximum Safe Operation Area

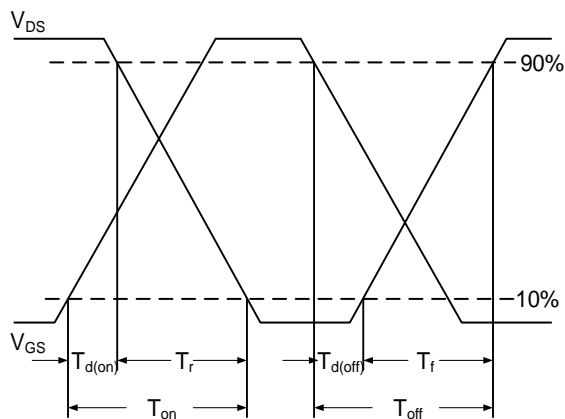


Fig.11 Switching Time Waveform

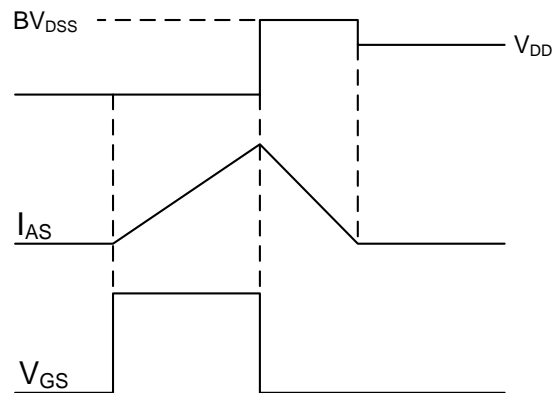
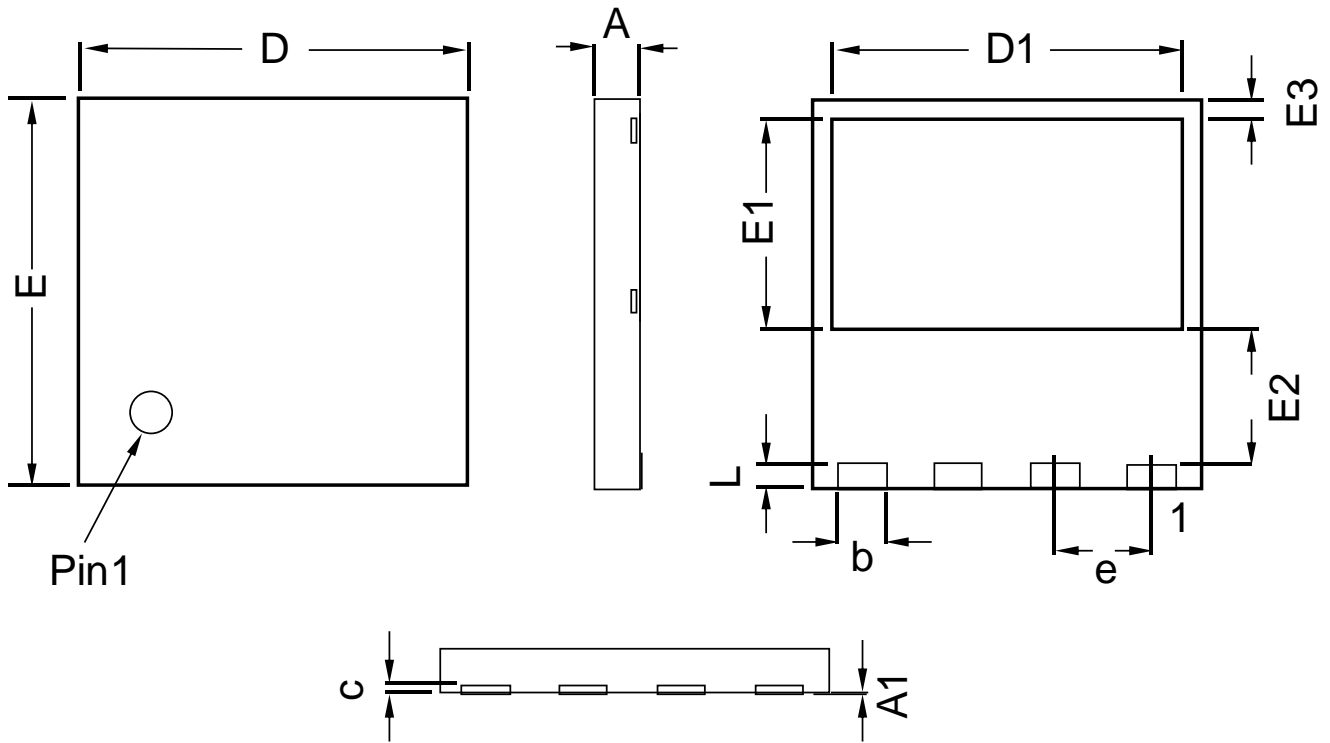


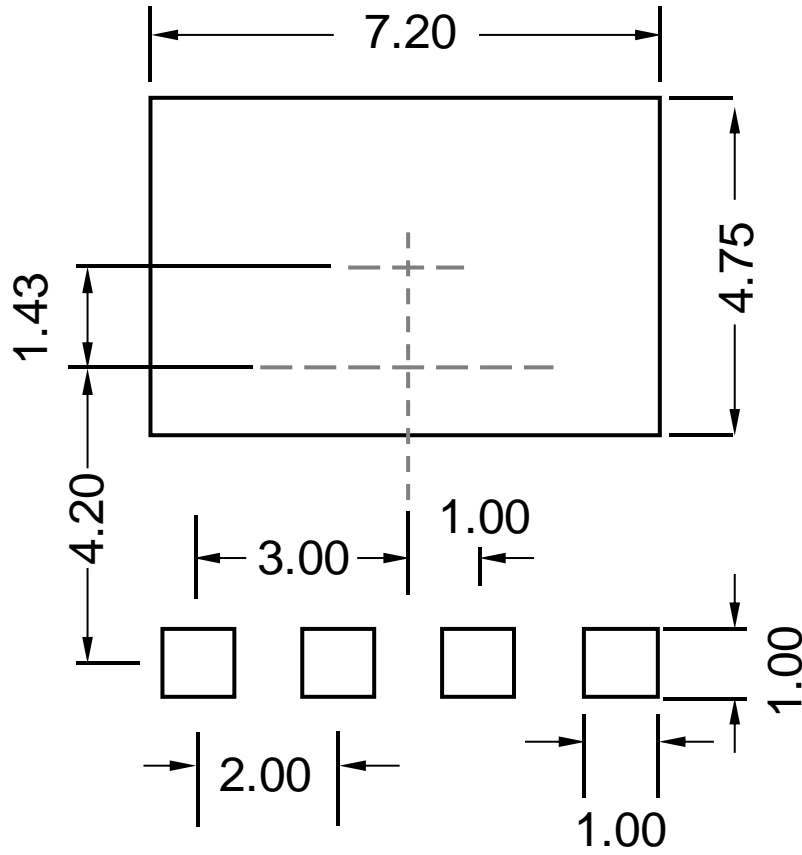
Fig.12 EAS Waveform

DFN8X8 PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 0.900 | 1.100 | 0.035 | 0.043 |
| A1 | 0.000 | 0.050 | 0.000 | 0.002 |
| b | 0.900 | 1.100 | 0.035 | 0.043 |
| c | 0.100 | 0.300 | 0.004 | 0.012 |
| D | 7.900 | 8.100 | 0.311 | 0.319 |
| D1 | 7.100 | 7.300 | 0.280 | 0.287 |
| E | 7.900 | 8.100 | 0.311 | 0.319 |
| E1 | 4.200 | 4.450 | 0.165 | 0.175 |
| E2 | 2.600 | 2.850 | 0.102 | 0.112 |
| E3 | 0.300 | 0.500 | 0.012 | 0.020 |
| e | 2.000 BSC | | 0.079 BSC | |
| L | 0.400 | 0.650 | 0.016 | 0.026 |

DFN8X8 RECOMMENDED LAND PATTERN



unit : mm